

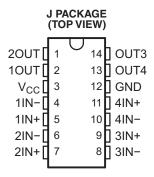
QUAD DIFFERENTIAL COMPARATOR

Check for Samples: LM139-SP, LM139A-SP

FEATURES

- QML-V Qualified, SMD 5962-7700801VCA, 5962-9673802VCA and 5962-9673802V9B
- Rad-Tolerant: 40 kRad/sec (Si) TID (5962-9673802VCA and 5962-9673802V9B) (1)
 - TID Dose Rate = 0.01 rad/sec (Si)
- Wide Supply Ranges
 - Single Supply: 2 V to 36 V (Tested to 30 V)
 - Dual Supplies: ±1 V to ±18 V (Tested to ±15 V)
- Low Supply-Current Drain Independent of Supply Voltage: 0.8 mA (Typ)
- Low Input Bias Current: 25 nA (Typ)
- Low Input Offset Current: 3 nA (Typ) (LM139)
- Low Input Offset Voltage: 2 mV (Typ)
- (1) Radiation tolerance is a typical value based upon initial device qualification with dose rate = 0.01 rad/sec. Radiation lot acceptance testing is available - contact factory for details.

- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS



DESCRIPTION/ORDERING INFORMATION

These devices consist of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible, as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM139 and LM139A are characterized for operation over the full military temperature range of -55°C to 125°C.

Table 1. ORDERING INFORMATION(1)

T _A	V _{IO} max AT 25°C	MAX V _{CC}	PACKAGE ⁽²⁾	ORDE	RABLE PART NUMBER	TOP-SIDE MARKING
	5 mV	30 V		LM139	5962-7700801VCA	5962-7700801VCA
–55°C to 125°C	2 mV	30 V	J	LM139A	5962-9673802VCA ⁽³⁾	5962-9673802VCA
	2 mV	30 V	KGD	5	5962-9673802V9B ⁽³⁾	N/A

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI
web site at www.ti.com.

(3) Radiation tolerant



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

⁽²⁾ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BON PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
15 mils	Silicon with backgrind	Floating	AlCu (0.5%)	0.055 mils

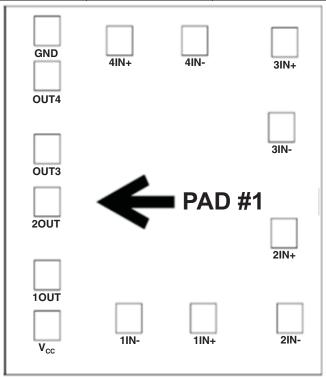
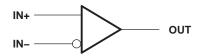


Table 2. Bond Pad Coordinates in Microns

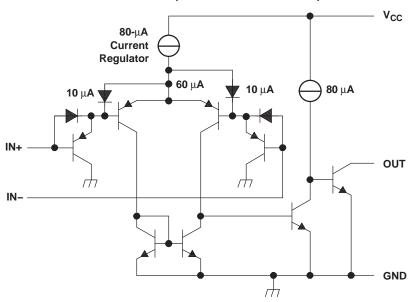
DISCRIPTION	PAD NUMBER	Xmin	Ymin	Xmax	Ymax
2OUT	1	22.86	455.93	124.46	557.53
1OUT	2	22.86	203.2	124.46	304.8
Vcc	3	22.86	27.94	124.46	129.54
1IN-	4	345.44	53.34	447.04	154.94
1IN+	5	640.08	53.34	741.68	154.94
2IN-	6	981.71	53.34	1083.31	154.94
2IN+	7	958.85	347.98	1060.45	449.58
3IN-	8	948.69	713.74	1050.29	815.34
3IN+	9	961.39	1008.38	1062.99	1109.98
4IN-	10	605.79	1013.46	707.39	1115.06
4IN+	11	308.61	1013.46	410.21	1115.06
GND	12	22.86	1047.75	124.46	1149.35
OUT4	13	22.86	891.54	124.46	993.14
OUT3	14	22.86	638.81	124.46	740.41



SYMBOL (EACH COMPARATOR)



SCHEMATIC (EACH COMPARATOR)



All current values shown are nominal.



ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage ⁽²⁾			36	V
V_{ID}	Differential input voltage (3)			±36	V
V_{I}	Input voltage range (either input)		-0.3	36	V
Vo	Output voltage			36	V
Io	Output current			20	mA
	Duration of output short circuit to ground (4)		Uı	nlimited	
θ_{JC}	Package thermal impedance, junction to case (5) (6)	J package		15.05	°C/W
TJ	Operating virtual-junction temperature			150	°C
	Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package		300	°C
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

All voltage values, except differential voltages, are with respect to network ground.

Differential voltages are at IN+ with respect to IN-.

Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction. Maximum power dissipation is a function of T_J (max), θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case (5) temperature is $P_D = (T_J (max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability. The package thermal impedance is calculated in accordance with MIL-STD-883.



ELECTRICAL CHARACTERISTICS FOR LM139

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS ⁽¹⁾	T _A ⁽²⁾	MIN	TYP	MAX	UNIT	
		$V_{CC} = 5 \text{ V to } 3$	0 V,	25°C		1			
V_{IO}	Input offset voltage	$V_{IC} = V_{ICR} min$ $V_{O} = 1.4 V$,	Full range			4	mV	
	Input offset current	V _O = 1.4 V		25°C		3	25		
I _{IO}	input onset current	V _O = 1.4 V		Full range			100	nA	
	lament bing grownest	V 4.4.V		25°C		-25	-100	nA l	
I _{IB}	Input bias current	$V_0 = 1.4 \text{ V}$		Full range			-300		
	Common-mode input-voltage			25°C	0 to V _{CC} - 1.5			.,	
V _{ICR}	range ⁽³⁾			Full range	0 to V _{CC} - 2			V	
A _{VD}	Large-signal differential-voltage amplification	V _{CC+} = ±7.5 V, V _O = -5 V to 5 V		25°C	50	200		V/mV	
	High level entent entent	V 4.V	V _{OH} = 5 V	25°C		0.1		nA	
I _{OH}	High-level output current	$V_{ID} = 1 V$	V _{OH} = 30 V	Full range			1	μA	
		., .,		25°C		150	400		
V_{OL}	Low-level output voltage	$V_{ID} = -1 V$,	$I_{OL} = 4 \text{ mA}$	Full range			700	mV	
I _{OL}	Low-level output current	$V_{ID} = -1 V$,	V _{OL} = 1.5 V	25°C	6	16		mA	
I _{CC}	Supply current (four comparators)	V _O = 2.5 V,	No load	25°C		0.8	2	mA	

⁽¹⁾ All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽²⁾ Full range (MIN to MAX) for LM139 and LM139A is –55°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽³⁾ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.



ELECTRICAL CHARACTERISTICS FOR LM139A

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS ⁽¹⁾	T _A ⁽²⁾	MIN	TYP ⁽³⁾ MAX	UNIT	
I _{CC}	Supply current	R _L = ∞, V+ = 30 V	Full range		2	mA	
I _{CEX}	Output leakage current	V+ = 30 V, V _{OUT} = 30 V	Full range		1	μA	
. ,	O		25°C		400		
V_{SAT}	Saturation voltage	I _{SINK} = 4 mA	Full range		700	mV	
I _{SINK}	Output sink current	V _{OUT} = 1.5 V	25°C		6	mA	
		V. 5.V.V. 6.V.	25°C		±2	mV	
		$V+ = 5 V, V_{CM} = 0 V$	Full range		±4		
			25°C		±2		
		$V+ = 30 \text{ V}, V_{CM} = 0 \text{ V}$	Full range		±4	mV	
V _{IO}	Input offset voltage	V+ = 30 V, V _{CM} = 28.5 V, V _{OUT} = 1.5 V	25°C		±2	mV	
		V+ = 30 V, V _{CM} = 28 V, V _{OUT} = 1.5 V	Full range		±4	mV	
I _{IB}	logue bigg gurrant	V 4.5.V	25°C	-100	-1	nA	
	Input bias current	V _{OUT} = 1.5 V	Full range	-300	-1		
	land offers account	V 45V	25°C		±25	nA	
I _{IO}	Input offset current	V _{OUT} = 1.5 V	Full range		±100		
PSRR	Power supply rejection ratio	V+ = 5 V to 30 V	25°C	60	100	dB	
CMRR	Common-mode rejection ratio	V+ = 30 V, $V_{CM} = 0 V \text{ to } 28.5 V$	25°C	60		dB	
A_V	Voltage gain	V+ = 15 V, $R_L ≥ 15 kΩ$, $V_{OUT} = 1 V to 11 V$	25°C	50		V/mV	
. (4)	0	.,	25°C	0	V+ - 1.5		
V _{CM} ⁽⁴⁾	Common mode voltage range	V+ = 30 V	Full range	0	V+ - 2	V	
V _{DIFF} ⁽⁵⁾	Differential input voltage	V+ = 30 V, V- = 0 V, V _{IN+} = 36 V, V _{IN-} = 0 V	Full range		500	nA	
V DIFF `°'	Dinerential input voltage	$V+ = 30 V, V- = 0 V, V_{IN+} = 0 V, V_{IN-} = 36 V$	Full range		500	IIA	
<u> </u>	Posnonco timo	V _{OD} (overdrive) = 5 mV	25°C		5		
t _{RLH}	Response time	V _{OD} (overdrive) = 50 mV	25 C		0.8	μs	
	Decrease time	V _{OD} (overdrive) = 5 mV	25°C		2.5		
t _{RHL}	Response time	V _{OD} (overdrive) = 50 mV	25°C		0.8	μs	

All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. MAX V_{CC} for testing purposes is 30 V. Full range is −55°C to 125°C for LM139A.

All typical values are at $T_A = 25$ °C.

The input common mode voltage or either input signal voltage should not be allowed to go negative by more that 0.3 V. The upper end of the common mode voltage range is V+ -1.5 V for T_A = 25°C or V+ -2.0 V for T_A = Full range, but either or both inputs can go to +30 V dc without damage independent of the magnitude of V+.

Positive excursions of input voltage may exceed the power supply level. As long as the other voltage remains within the common mode range, the comparator will provide a proper output state. The low input voltage state must not be less than -0.3 V dc or 0.3 V dc below the magnitude of the negative power supply, if used.

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SWITCHING CHARACTERISTICS

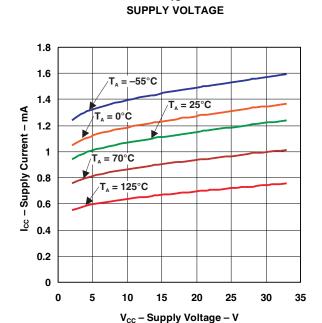
 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST COM	TYP	UNIT	
Dogganas timo	R_L connected to 5 V through 5.1 k Ω ,	100-mV input step with 5-mV overdrive	1.3	
Response time	0 45 = 5(1) (2)	TTL-level input step	0.3	μs

 ⁽¹⁾ C_L includes probe and jig capacitance.
 (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

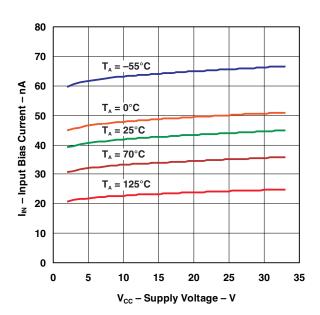


TYPICAL CHARACTERISTICS

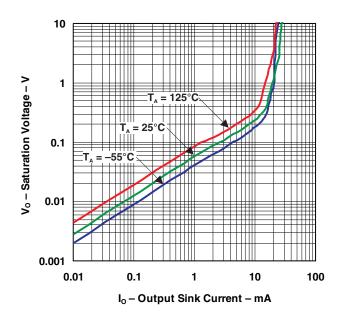


SUPPLY CURRENT

INPUT BIAS CURRENT vs SUPPLY VOLTAGE



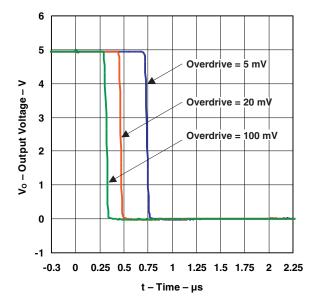
OUTPUT SATURATION VOLTAGE



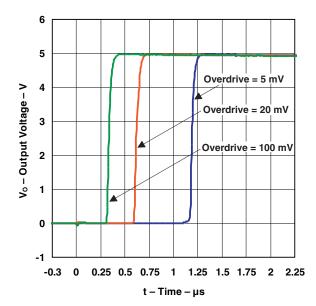


TYPICAL CHARACTERISTICS (continued)

RESPONSE TIME FOR VARIOUS OVERDRIVES NEGATIVE TRANSITION



RESPONSE TIME FOR VARIOUS OVERDRIVES POSITIVE TRANSITION



23-Mar-2012

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-7700801VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
5962-9673802V9B	ACTIVE	XCEPT	KGD	0	1	TBD	Call TI	N / A for Pkg Type	
5962-9673802VCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF LM139-SP:

Catalog: LM139

NOTE: Qualified Version Definitions:



23-Mar-2012

Catalog - TI's standard catalog product

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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